

Method for the alignment of substrates before bonding

A b s t r a c t

The invention relates to a method for the alignment of a first substrate (7) comprising at least two first alignment marks (8) with a second substrate (7') comprising at least two second alignment marks (8'), wherein,

- by means of a first assignment, the first alignment marks (8) are assigned to at least two first characteristic alignment features (9) of the first substrate (7) in an X-direction and in a Y-direction,
- by means of a second assignment, the second alignment marks (8') are assigned to at least two second characteristic alignment features (9') of the second substrate (7') in an X-direction and in a Y-direction and
- by means an alignment, the first (8) and second alignment marks (8') are aligned in relation to one another in an X- and Y-direction by means of the first and second characteristic alignment features (9, 9').

Furthermore, the present invention relates to a corresponding device.

Figure 2c